ITEQ Corporation

2020 Third Quarter Earnings Result

ITEQ

INNOVATION. TEAMWORK. EXCELLENCE. QUALITY

Disclaimer Statement



- This presentation and release contain "forward-looking statements" which may include projections
 of future results of operations, financial condition or business prospects based on our own
 information and other sources.
- Our actual results of operations, financial condition or business prospects may differ from those expressed or implied in these forward-looking statements for a variety of reasons, including but not limited to market demand, price fluctuations, competition, international economic conditions, supply chain issues, exchange rate fluctuations and other risks and factors beyond our control.
- The forward-looking statements in this release reflect the current belief of ITEQ as of the date of this release. ITEQ undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.

Company Overview

◆ Establishment: April 10th, 1997

◆ Headquarter: HsinChu, Taiwan

◆ Capital: NTD\$3,330M

◆ Employees: Over 3,000

Chairman: Dennis Chen

◆ CEO: Audrey Tsai

◆ Main Product: Copper Clad Laminate & Prepreg

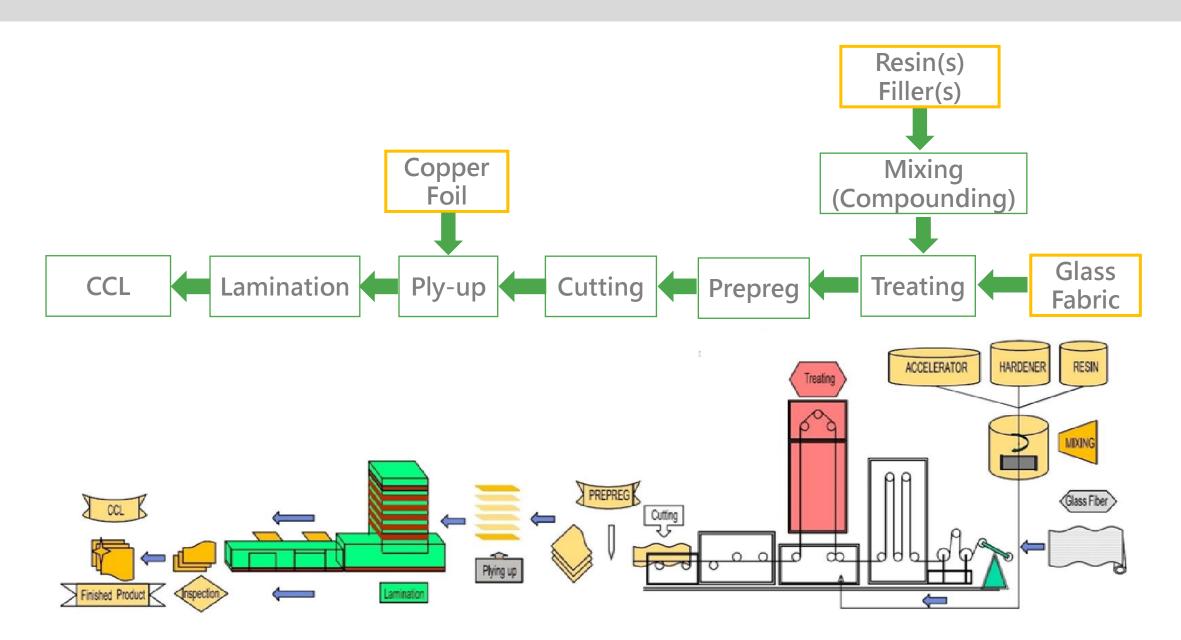
Flexible CCL

Masslam service



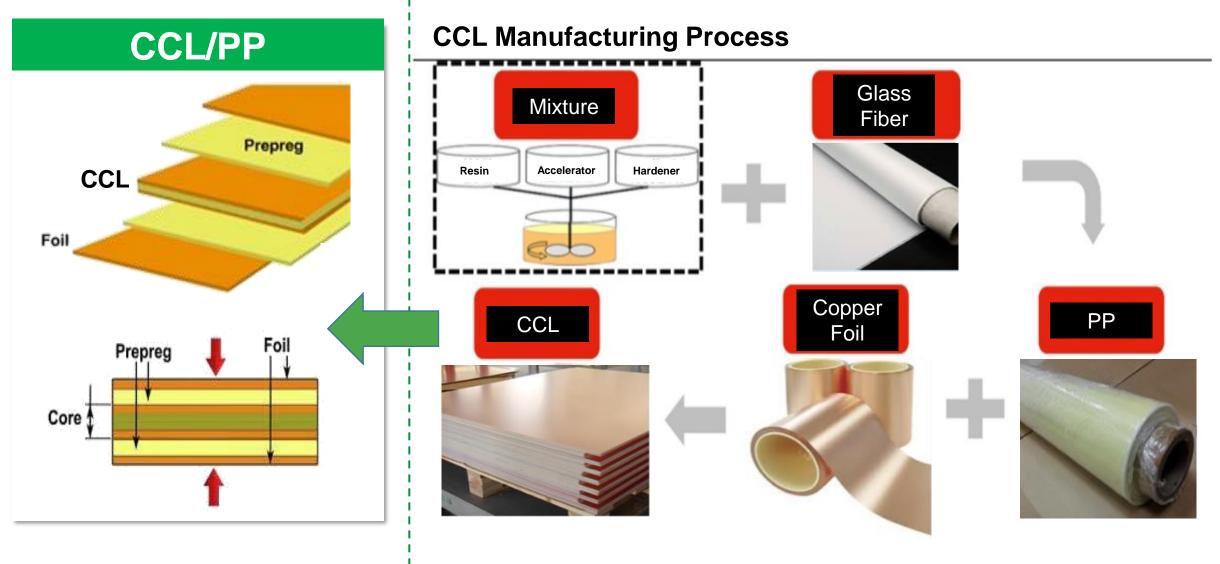
CCL & PP Manufacturing Flow





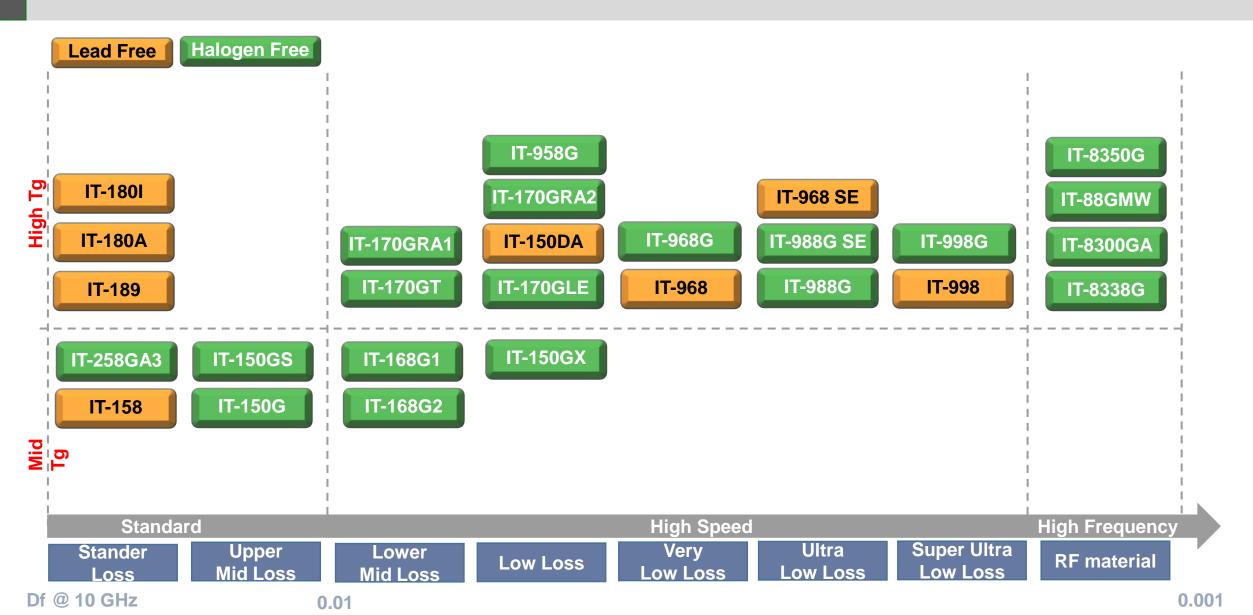
CCL & PP Composite Structure





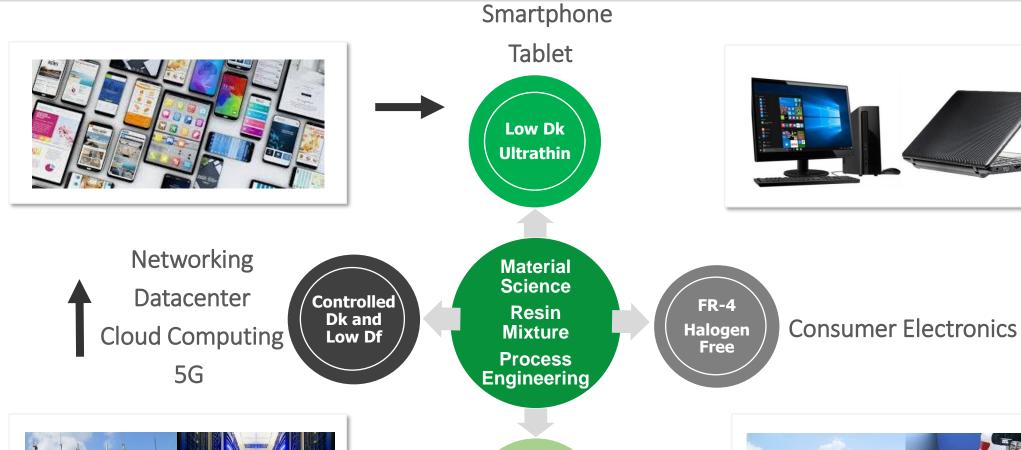
Product Roadmap





Core Technology





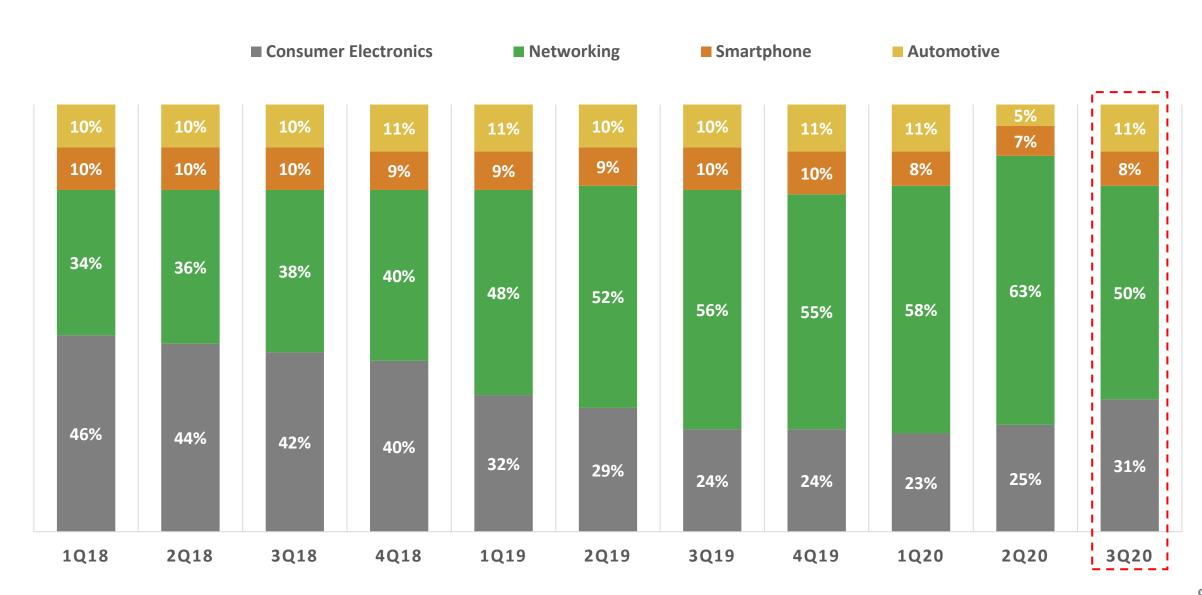






1Q18~3Q20 Product Mix

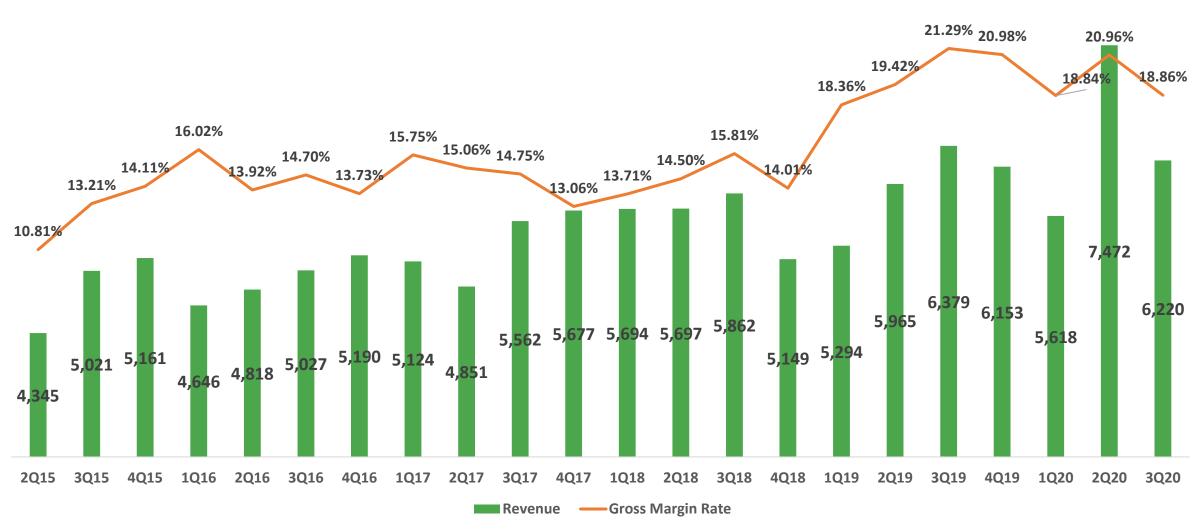




Revenue & Gross Margin Rate

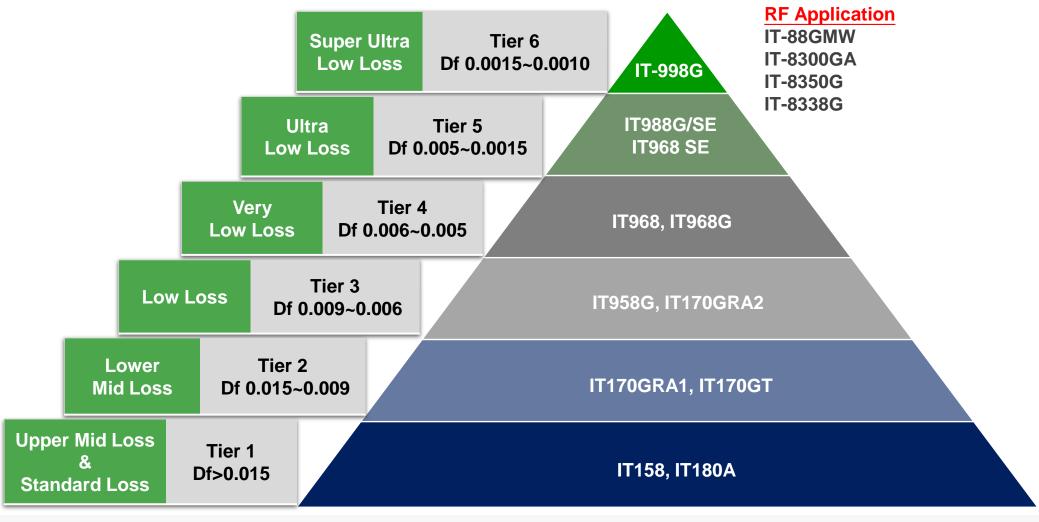


(Million \$NTD)



Well-Expanded Product Line





- The need for 5G commercialization and server upgrade will expedite the growth of high speed / frequency demand
- ITEQ's market share in high speed / frequency material to uplift robustly

3Q20 Income Statement

Effective Tax Rate

Net Margin



NTD \$Million	3Q20	2Q20	3Q19	QoQ	YoY
Revenue	6,220	7,472	6,379	-17%	-2%
Gross Profit	1,173	1,567	1,358	-25%	-14%
Operating Expense	454	486	421	-7%	8%
Operating Profit	719	1,081	938	-33%	-23%
Non-Op Income / Loss	97	(4)	(59)		
Income before Tax	816	1,077	878	-24%	-7%
Tax Expense	172	211	163		
Net Income to Parent	645	866	715	-26%	-10%
EPS(NT\$)	1.94	2.60	2.36	-25%	-18%
Key Financial Ratio					
Gross Margin	18.9%	21.0%	21.3%		
Operating Expense Ratio	7.3%	6.5%	6.6%		
Operating Margin	11.6%	14.5%	14.7%		

19.6%

11.6%

18.5%

11.2%

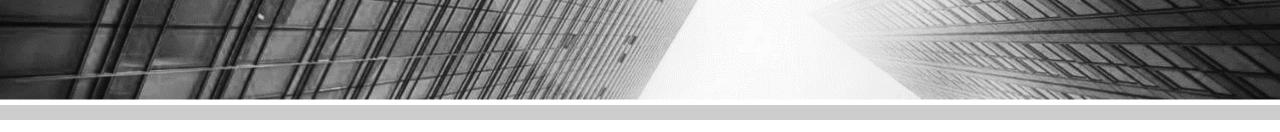
21.0%

10.4%

3Q20 Balance Sheet



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NTD \$Million	3Q20	2Q20	3Q19
Total Assets	25,953	24,433	21,929
Cash	3,625	2,566	2,984
Marketable Securities	6	11	83
NR / AR	11,200	11,958	10,702
Inventories	3,330	3,199	2,110
Fixed Assets	5,896	4,762	4,596
Total Liabilities	13,527	12,861	13,476
Short-term Debt	2,331	1,359	4,242
NP / AP	6,328	6,293	5,715
Long-term Debt	1,640	919	718
Total Equity	12,426	11,572	8,453
Key Financial Index			
Days Sales Outstanding	156	161	151
Days Sales of Inventory	56	55	37
Days Payable Outstanding	111	109	97
ROE (%)	23.90	25.6	29.20
ROA (%)	10.57	11.2	12.08
Debt ratio (%)	52.12	52.6	61.45
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Market Trend & Growth Drivers





Hunger for High Speed Transmission

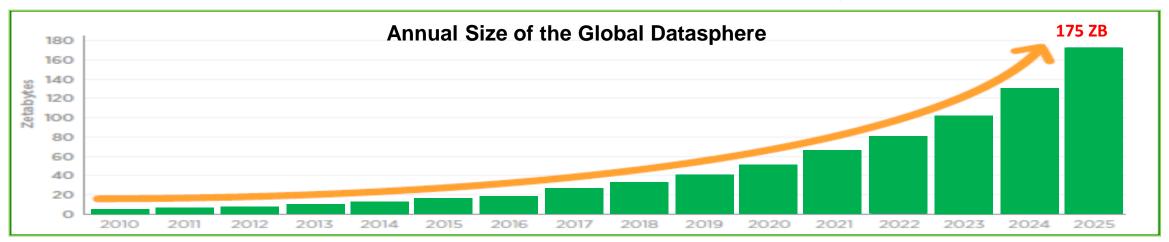


Rapid expansion of Global Datasphere

- Core (traditional and cloud datacenters)
- Edge (enterprise-hardened infrastructure such as, server rooms, servers in the field, cell towers, and smaller datacenters etc.)
- Endpoint (PCs, smartphones, and IoT devices)

Fast growing Global IP traffic

- UHD video streaming and internet gaming
- Connected home, work, health and car
- Big data and Al applications
- Cloud computing and cloud storage
- Virtual Reality (VR) and Augmented Reality (AR)



(Source: Data Age 2025, sponsored by Seagate with data from IDC Global DataSphere, May 2020)

 Rapid growth of global data traffic stimulates equipment upgrade to meet the need of low latency, high reliable and high speed computing

5G Network Infrastructure & Opportunities



Core (Telecom) + Transport Network:

- Including data center, Edge computing, OTN
- High efficient computing and massive data traffic

High Speed Material

Distributed + Centralized Unit (DU+CU)

- Including Macro Cell, Micro Cell to Small Cell
- Low latency and high speed requirements

High Speed Material

Active Antenna Unit (AAU)

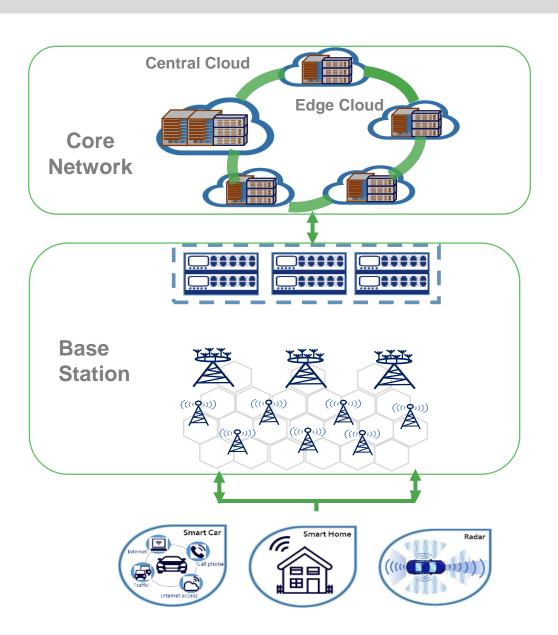
- Including Antenna, PA, TRX Network
- Multi layer design for complex functionality

High Speed Material

High Frequency Material

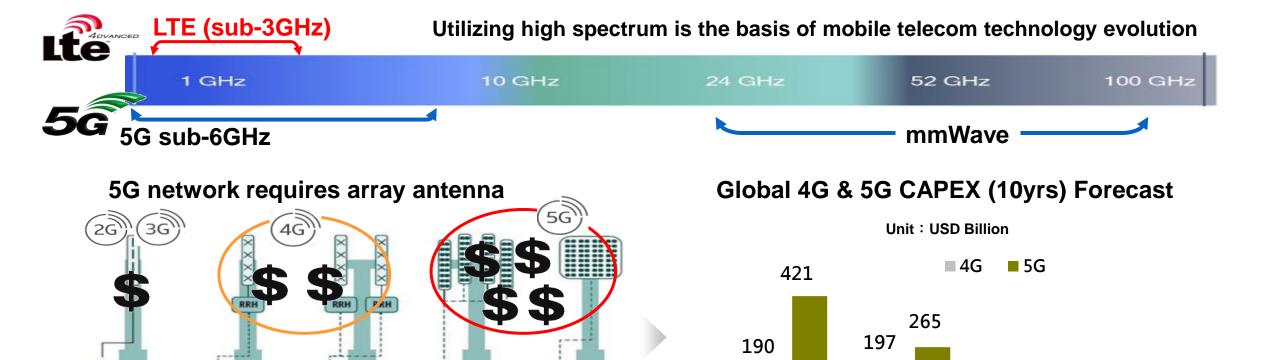
loT(Internet of Things)

High Speed Material



Sustainable Growth Momentum (Telecom)





CHINA

USA

KOREA

Source : Morgan Stanley \cdot 2019/2 ; DIGITIMES Research \cdot 2020/8

Fronthaul

Fronthaul

Beamforming

Fiber

Single Antenna 2x2/4x4 MIMO Antennas

Fronthaul

Coax

• High Spectrum 5G Network: Need base station equipment MP/upgrade to drive the demand of high speed/frequency material to grow

Fiber

Fronthaul

Massive MIMO Antennas /

Design Complexity of PCB: Increase area and layer counts for PCB to bring up the unit of demand for CCL

JAPAN

Sustainable Growth Momentum (Datacom)



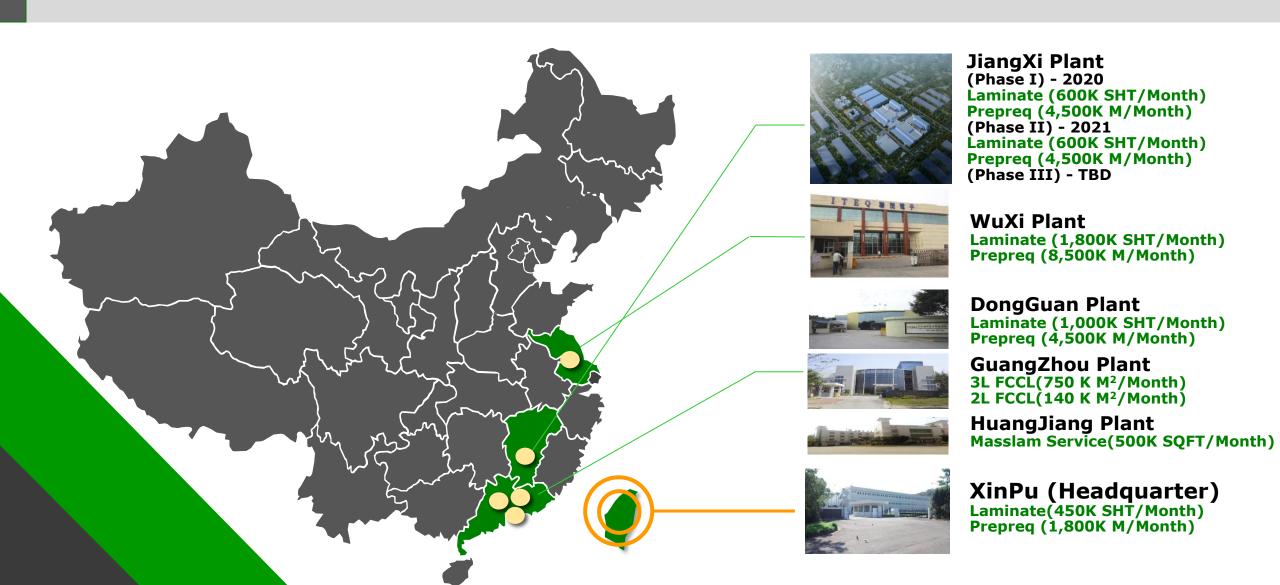




- Increase of Datacenter Equipment Shipment: Demand of high speed material to grow correlatively
- Hardware Equipment Upgrade: Corresponding CCL material to upgrade

Manufacturing Site & Capacity





2014 – 2019 Dividend Policy



Year	EPS(NT\$)	Dividend(NT\$)	Cash Dividend(NT\$)	Pay-out Ratio(%)
2014	1.62	1.2	1.2	74%
2015	1.92	1.6	1.6	83%
2016	3.13	2.5	2.5	80%
2017	4.11	3.1	3.1	75%
2018	5.86	3.8	3.8	65%
2019	8.13	5.0	5.0	62%

^{*}New shares issuance of 30 million common shares concluded in March 31st 2020; current total outstanding common share: 333 million



ITEQ & MGC Joint Venture Project

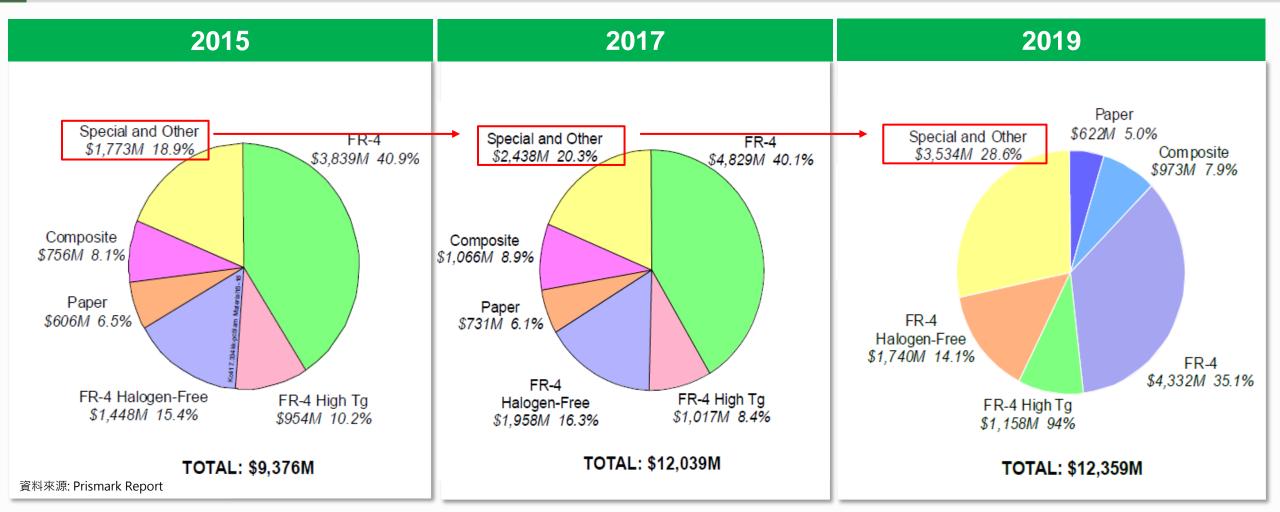




Increase of Special CCL Production Value



Global CCL Production Value (\$USD)



- High Speed Transmission: Global special laminates production value increased to \$3,534M in 2019 from \$1,773M in 2015
- Leadership of High Speed/Frequency Technology: ITEQ to set footprint in IC substrate materials adopted in the semiconductor packaging applications

ITEQ x MGC JV – IC Substrate Material



MGC

IC Packaging Laminate

MGC & ITEQ

IC Substrate Material **ITEQ**

High
Speed/Frequency CCL



BT Substrate

- Logic IC (Consumer Electronic, Smartphone, GPU, CPU)
- Memory IC (DRAM, NAND Flash)

